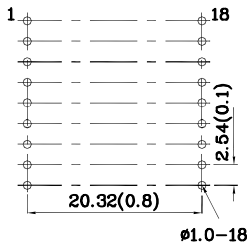


Features

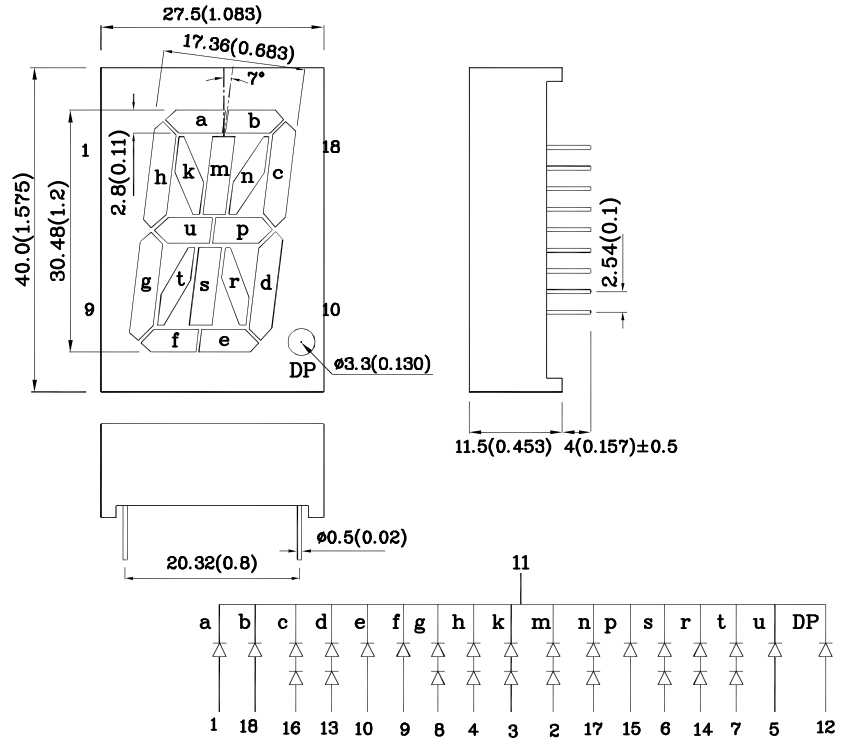
- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



RECOMMENDED PCB LAYOUT



Package Schematics



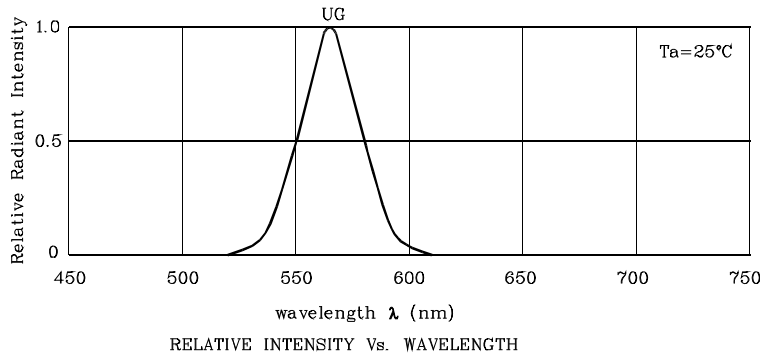
Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

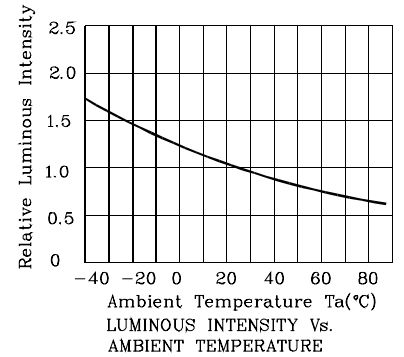
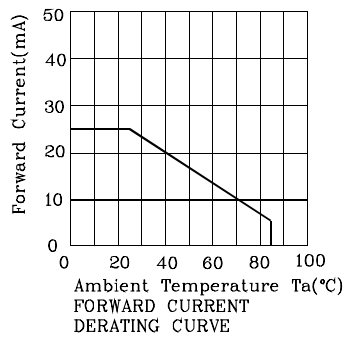
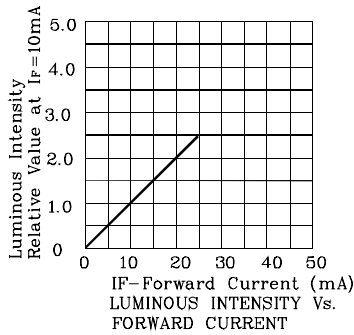
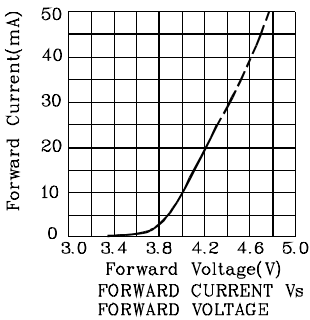
Absolute Maximum Ratings (TA=25°C)		UG (GaP)	Unit	
Reverse Voltage	c,d,g,h,k,m,n, s,r,t	VR	5	V
	a,b,e,f,p,u and DP		5	
DC Forward Current	c,d,g,h,k,m,n, s,r,t	IF	25	mA
	a,b,e,f,p,u and DP			
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	c,d,g,h,k,m,n, s,r,t	iFS	140	mA
	a,b,e,f,p,u and DP			
Power Dissipation	c,d,g,h,k,m,n, s,r,t	PD	125	mW
	a,b,e,f,p,u and DP		62.5	
Operating Temperature	TA		-40 ~ +85	°C
Storage Temperature	Tstg		-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]			260°C For 3~5 Seconds	

Operating Characteristics (TA=25°C)			UG (GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	c,d,g,h,k,m,n, s,r,t	VF	4.0	V
	a,b,e,f,p,u and DP		2.0	
Forward Voltage (Max.) (IF=10mA)	c,d,g,h,k,m,n, s,r,t	VF	5.0	V
	a,b,e,f,p,u and DP		2.5	
Reverse Current (Max.) (VR=5V)	c,d,g,h,k,m,n, s,r,t	IR	10	uA
	a,b,e,f,p,u and DP			
Wavelength of Peak Emission (Typ.) (IF=10mA)	λP		565	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)	λD		568	nm
Spectral Line Full Width At Half- Maximum (Typ.)(IF=10mA)	$\Delta\lambda$		30	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C		15	pF

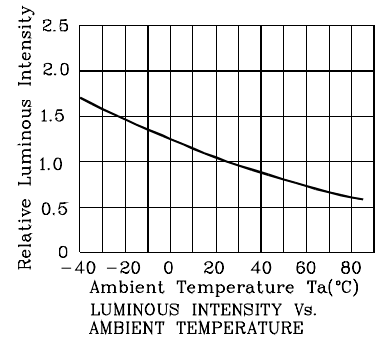
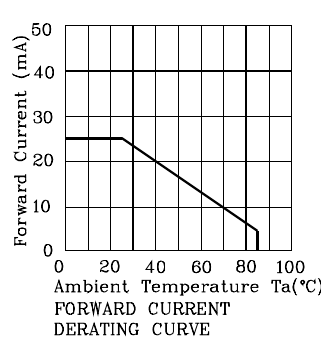
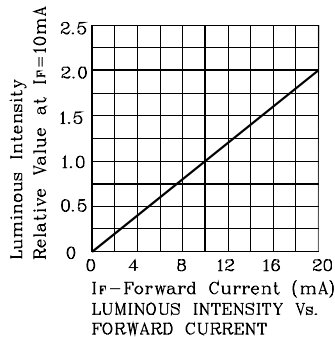
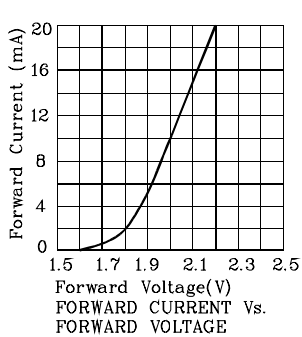
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _f =10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XAUG30C	Green	GaP	3600	8190	565	Common Cathode, Rt. Hand Decimal.



❖ UG

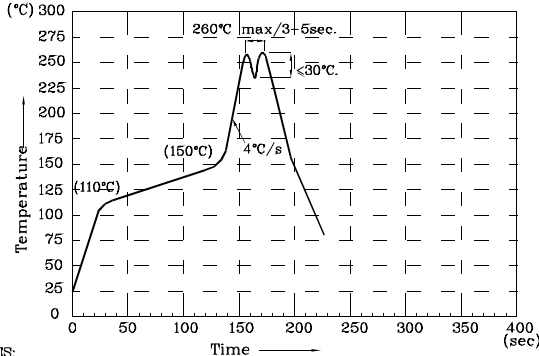


Note:the curves are on the segment c,d,g,h,k,m,n,s,r and t.



Note:the curves are on the segment a,b,e,f,p,u and DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

